

LTM8054-BGA-PBF 88LD 15mm X 11.25mm X 3.42mm (TABLE OF MATERIAL DECLARATION)
This package is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1839	Barium Compounds	7727-43-7	0.00478	2.60
				Bismaleimide/Triazine/Resin/Filler Substance(Silica Crystalline)	105391-33-1,1156-51-2 0/9003-36-5/21645-51-2	0.03558	19.35
				Copper Metal	7440-50-8	0.10261	55.80
				Copper Compounds	147-14-8	0.00042	0.23
				Ecotoxic substances	7440-38-2, 7440-28-0	0.00002	0.01
				Gold metal or alloy	7440-57-5	0.00029	0.16
				Nickel	7440-02-0	0.00142	0.77
				Zinc	7440-66-6	0.00020	0.11
				Continuous Filament Fiber Glass	65997-17-3	0.02795	15.20
				Acrylic Resin	non-disclosure	0.00912	4.96
				Epoxy Resin	non-disclosure	0.00003	0.02
				Chromium(III) Oxide	1308-38-9	0.00001	0.00
				Silica amorphous	7631-86-9	0.00010	0.05
				Talc;not containing fibers like asbestos	14807-96-9	0.00055	0.30
				Aromatic Carbonyl compounds	non-disclosure	0.00051	0.28
				Cyanoguanidine	461-58-5	0.00001	0.01
				Calcium carbonate	471-34-1	0.00001	0.00
				Amine compounds	non-disclosure	0.00007	0.04
				Leveling agent and others	non-disclosure	0.00020	0.11
2	Solder Paste	Alloy	0.1207	Sn	7440-31-5	0.11471	95.00
				Sb	7440-36-0	0.00604	5.00
3	Passive/Active Components		0.2870	Ni Oxide	1313-99-1	0.02387	8.32
				Cu Oxide	1317-38-0	0.00803	2.80
				Zn Oxide	1314-13-2	0.03635	12.67
				Fe Oxide	1317-61-9	0.13247	46.16
				Iron Powder (Fe)	7439-89-6	0.00388	1.35
				Copper (Cu)	7440-50-8	0.05935	20.68
				Nickel (Ni)	7440-02-0	0.00229	0.80
				Tin (Sn)	7440-31-5	0.00427	1.49
				Ceramic (Ba) Compounds	12047-27-7	0.01647	5.74
4	Active Ics	Silicon	0.0047	Silicon	7440-21-3	0.00470	100.00
5	Wire	Gold	0.0002	Au	7440-57-5	0.00021	99.99
6	Solder Ball	Alloy	0.1965	Sn	7440-31-5	0.18960	96.50
				Ag	7440-22-4	0.00589	3.00
				Cu	7440-50-8	0.00098	0.50
7	Encapsulation	Epoxy Resin	1.0726	Fused Silica	60676-86-0	0.82804	77.20
				Epoxy Resin	non-disclosure	0.09546	8.90
				Phenol Resin	non-disclosure	0.09546	8.90
				Crytalline Silica	14808-60-7	0.03218	3.00
				Carbon Black	1333-86-4	0.00536	0.50
				Metal Hydroxide	non-disclosure	0.01609	1.50
Total Package Weight			1.8657				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts